



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC110N06NS3 G		<b>Issued</b>		24. January 2018	
<b>MA#</b>				MA001275296					
<b>Package</b>				PG-TDSON-8-5		<b>Weight*</b>		123.96 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.296	1.05	1.05	10455	10455	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		92		
	non noble metal	iron	7439-89-6	0.038	0.03		305		
	non noble metal	copper	7440-50-8	37.762	30.46	30.50	304640	305037	
	non noble metal	copper	7440-50-8	0.059	0.05	0.05	475	475	
wire	non noble metal	copper	7440-50-8	0.059	0.05	0.05	475	475	
encapsulation	organic material	carbon black	1333-86-4	0.096	0.08		775		
	plastics	epoxy resin	-	6.823	5.50		55042		
	inorganic material	silicondioxide	60676-86-0	41.128	33.19	38.77	331801	387618	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.17	1.17	11711	11711	
plating	noble metal	silver	7440-22-4	0.166	0.13	0.13	1335	1335	
solder	non noble metal	tin	7440-31-5	0.029	0.02		237		
	noble metal	silver	7440-22-4	0.037	0.03		296		
	non noble metal	lead	7439-92-1	1.404	1.13	1.18	11324	11857	
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		27		
	non noble metal	iron	7439-89-6	0.011	0.01		91		
	non noble metal	copper	7440-50-8	11.320	9.13	9.14	91324	91442	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		54		
	non noble metal	iron	7439-89-6	0.022	0.02		180		
	non noble metal	copper	7440-50-8	22.292	17.98	18.01	179836	180070	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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